

SPECIFICATION

REFOND P/N

RF-A1A3F-R165-R1

R&D

Mass Production



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1. Description

1.1



The Red source color devices are made with AlGaInp on Substrate Light Emitting Diode .
Product Package:3.50mmX2.80mmX1.84mm.

LED AlGaInp

3.50mmX2.80mmX1.84mm.

1.2 Features

PLCC2 Package. PLCC2

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

SMT

Available on tape and reel.

Moisture sensitivity level: Level 2.

Level2

Compliance with RoHS and REACH.

RoHS REACH

Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101
Stress Test Qualification for Automotive Grade Discrete Semiconductors

AEC-Q101

1.3 Application

Automotive Interior Lighting.
Switches.



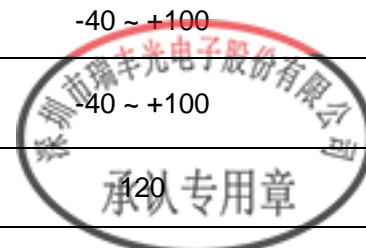
1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	$I_F=20mA$	1.8	2.0	2.5	V
Reverse Current	I_R	$V_R=5V$	---	---	10	μA
Luminous Intensity	I_V	$I_F=20mA$	800	1000	1500	mcd
Dominant wavelength	λ_d	$I_F=20mA$	615	617	620	nm
Viewing Angle	2 1/2	$I_F=20mA$	---	120	---	deg
Thermal Resistance.	R_{THJ-S}	$I_F=20mA$	---	---	260	/W

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Power Dissipation	P_D	75	mW
Forward Current	I_F	30	mA
Peak Forward Current	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Electrostatic Discharge (HBM)	E_{SD}	8000	V
Operating Temperature	T_{OPR}	-40 ~ +100	
Storage Temperature	T_{STG}	-40 ~ +100	
Junction Temperature	T_J	120	



Notes

1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. $\pm 0.1V$.
3. The above color coordinates measurement allowance tolerance is ± 0.005 . ± 0.005 .
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$. $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED
8. ESD yield is over 90% at 8000V ESD (HBM). ESD protection during products handling is needed. 90% LED
ESD8000V

1.6 Bin Range Of Forward Voltage and Luminous Intensity (IF=20mA)

BIN (IF=20mA)

Table 1-3

V _F	B1	B2	C1	C2	D1	D2	E1
	1.8-1.9	1.9-2.0	2.0-2.1	2.1-2.2	2.2-2.3	2.3-2.4	2.4-2.5
IV mcd	L1	L2	M1				
	800-1000	1000-1200	1200-1500				
WD(nm)	D1	D2					
	615-617.5	617.5-620					



1.7 Typical Optical Characteristics Curves

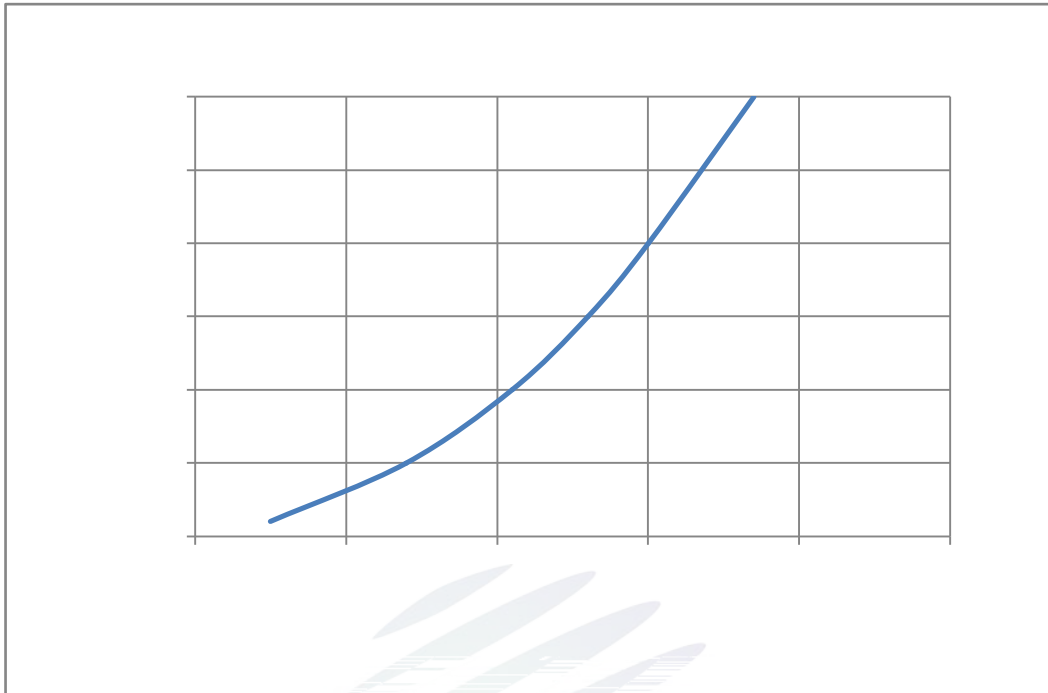


Fig. 1-7 Forward Voltage Vs Forward Current

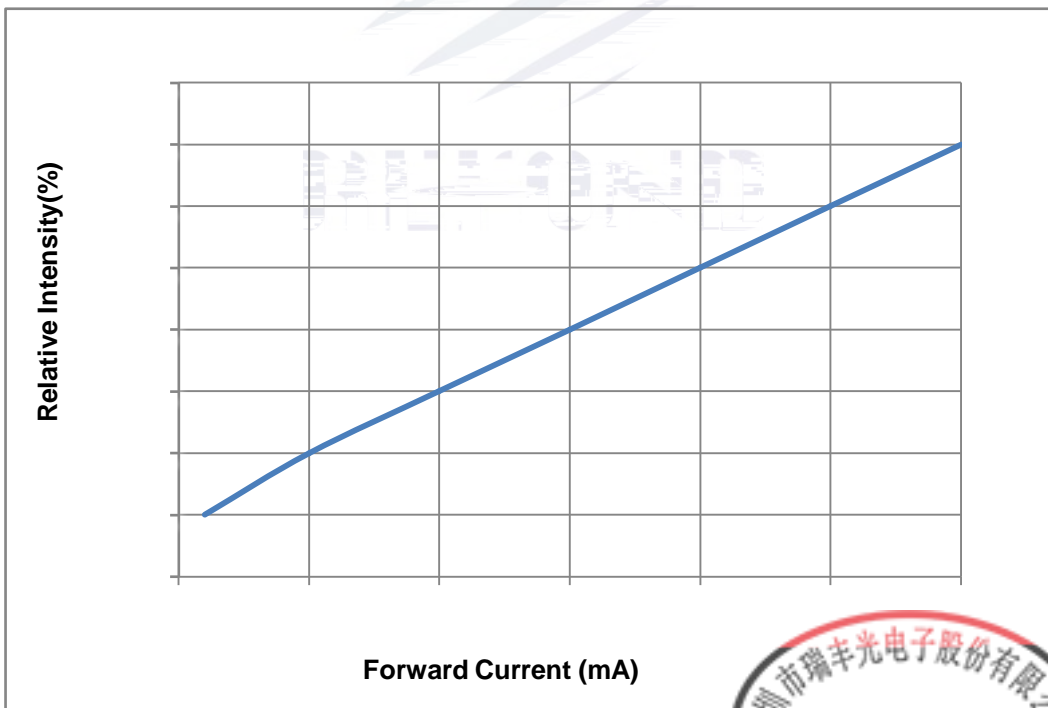


Fig. 1-8 Forward Current Vs Relative Intensity



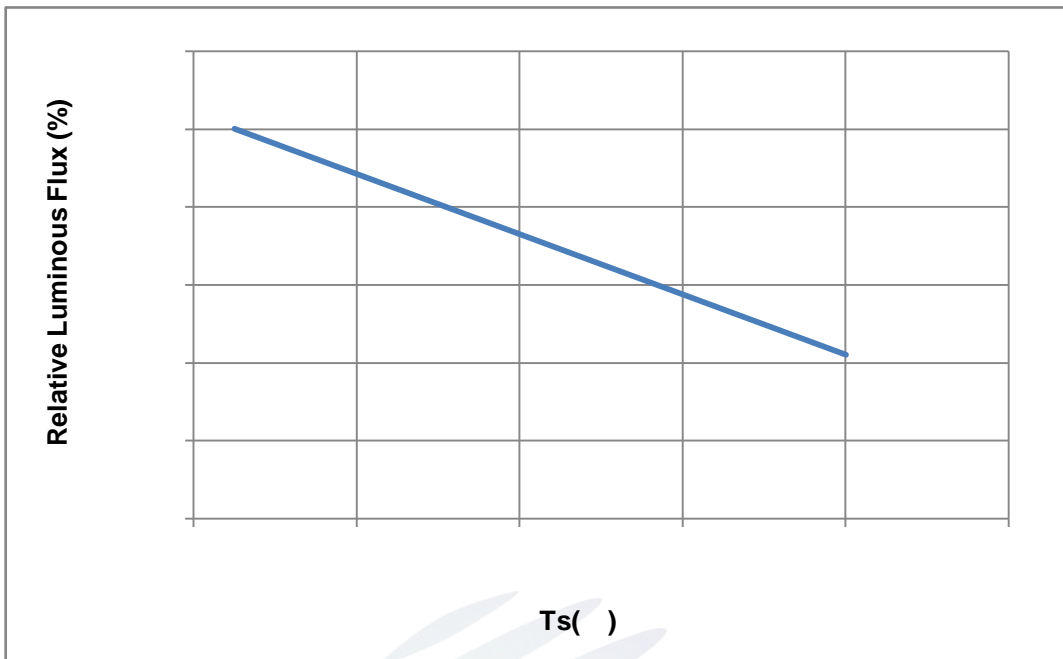


Fig. 1-9 Solder Temperature Vs Relative Intensity

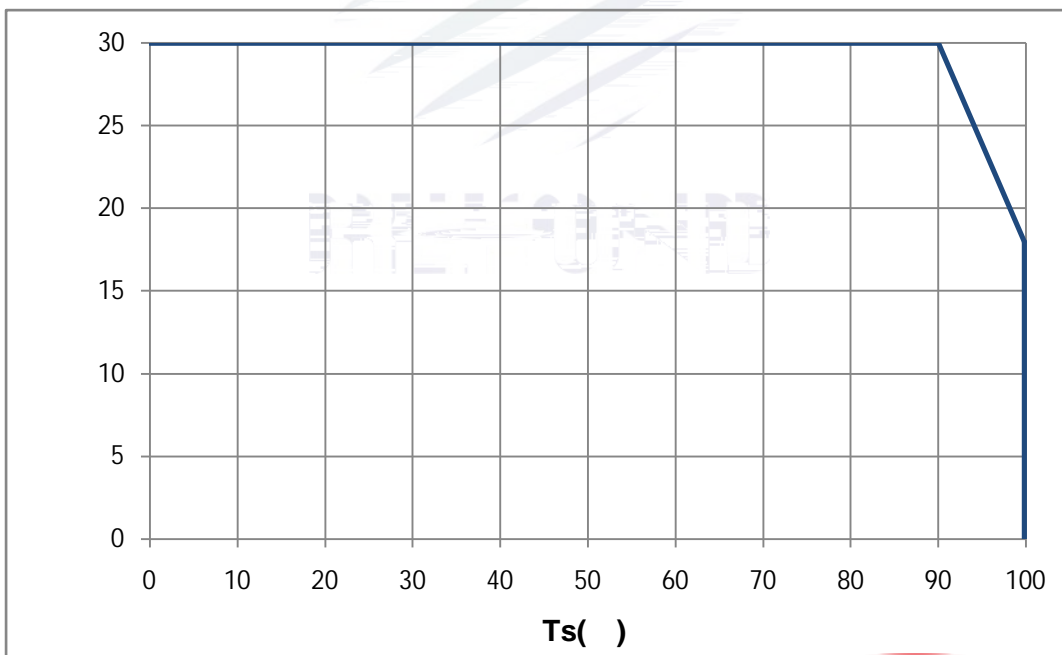


Fig. 1-10 Solder Temperature Vs Forward Current



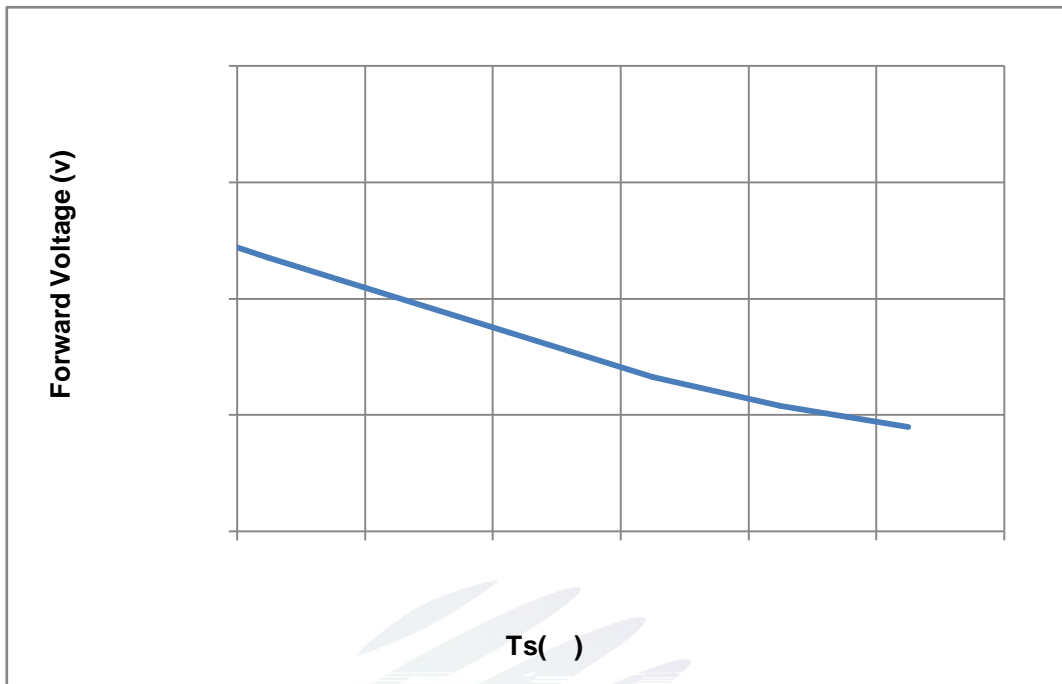


Fig. 1-11 Forward Voltage Vs Solder Temperature

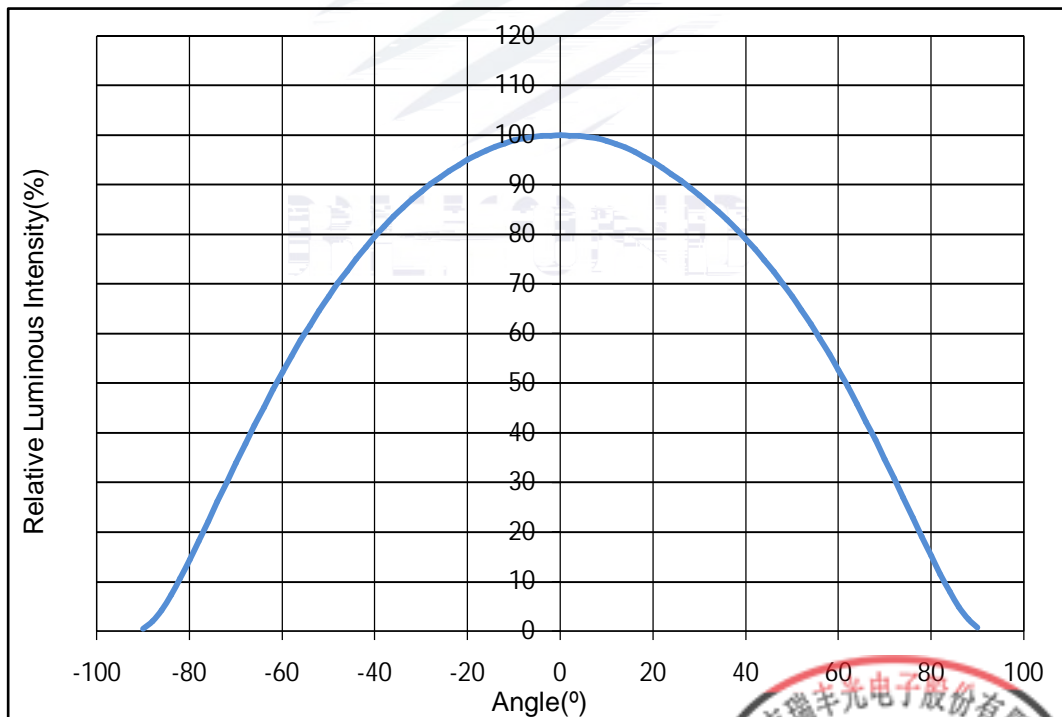
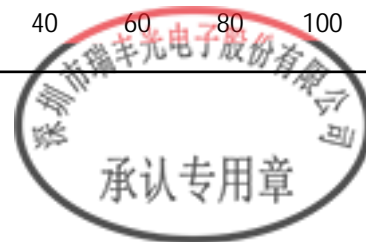


Fig. 1-12 Radiation diagram



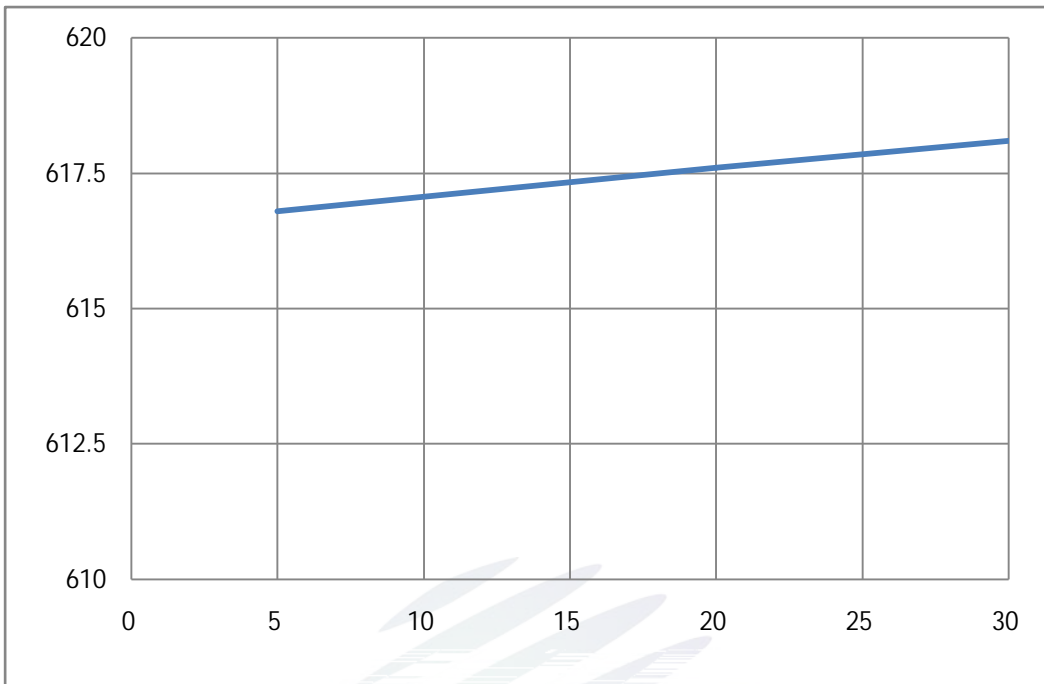


Fig. 1-13 Forward current vs. Dominate wavelength (Ts=25°C)

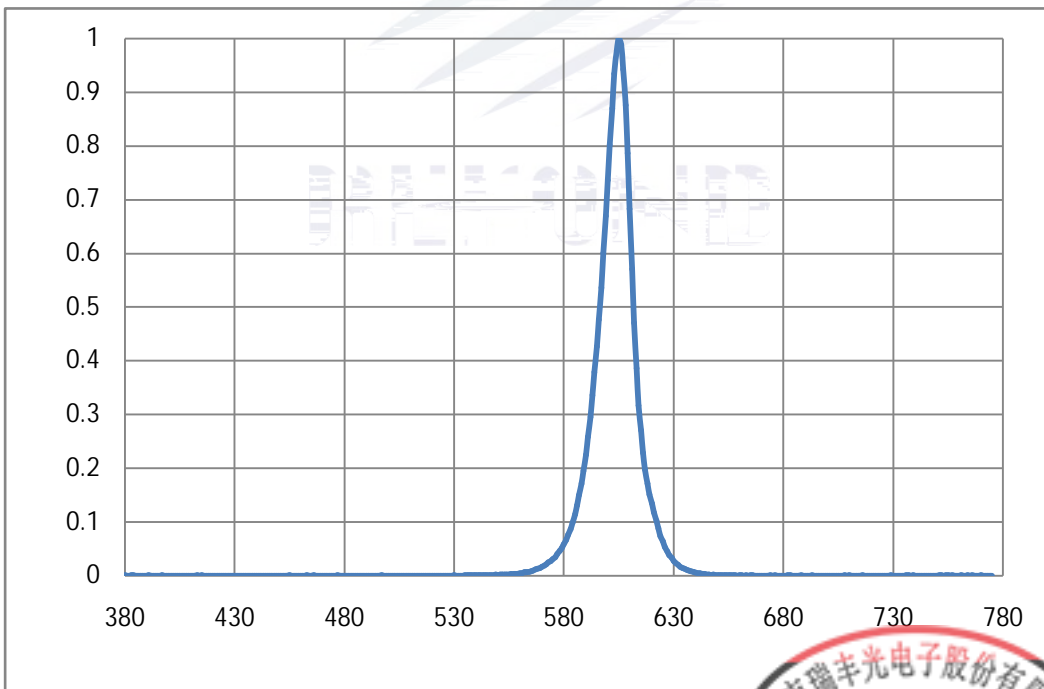
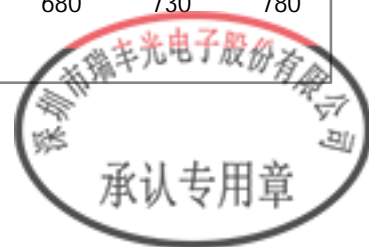


Fig. 1-14 Spectrum Distribution

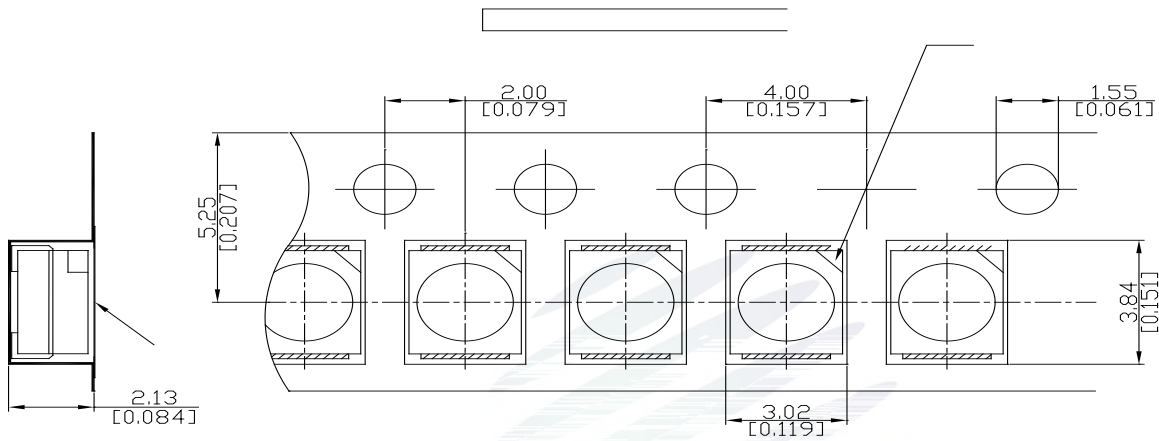


2. Packaging

2.1 Packaging Specification

Package:2000pcs/reel. 2000pcs

2.1.1 Carrier Tape Dimension mm



2.1.3 Label Form Specification

Table 2-2 Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V _F	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

Fig. 2-3 Label Form Specification

2.2 Moisture Resistant Packing



Fig.2-4 Moisture Resistant Packing

2.3 Cardboard Box

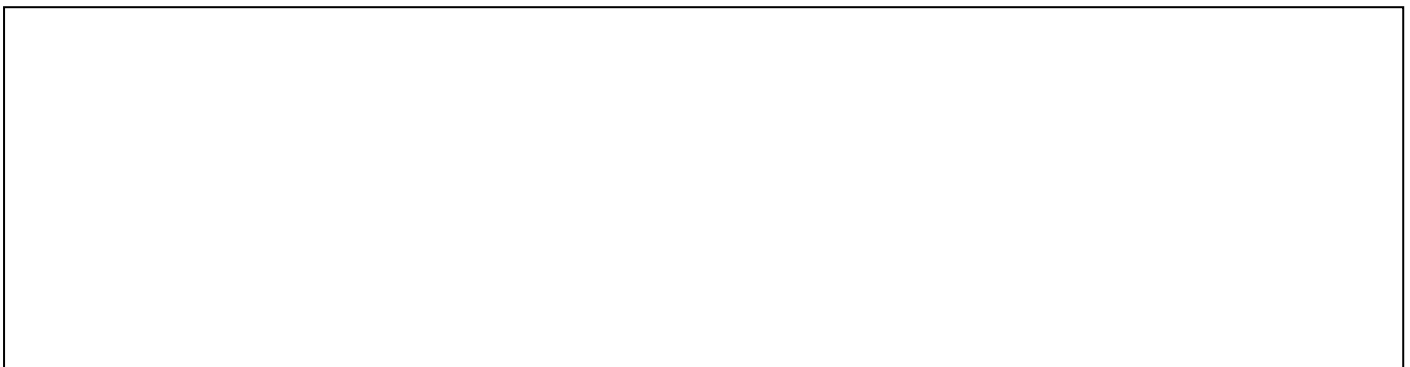


Fig.2- Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
MSL2 2	JESD22-A113	85 / 60%RH	168 hrs.	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min 10s 125 15min	1000 cycle	20pcs.	0/1
Life Test	JESD22-A108	Ta=100 If=20mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%RH If=20mA	1000hrs.	20pcs.	0/1



2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	$I_F=20mA$	-	U.S.L*)x1.1
Reverse Current	I_R	$V_R = 5V$	-	U.S.L*)x2.0
Luminous Flux		$I_F=20mA$	L.S.L*)x0.7	-

Notes

- 1.U.S.L: Upper standard level L.S.L: Lower standard level
- 2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. / LED
LED
- 3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.



3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

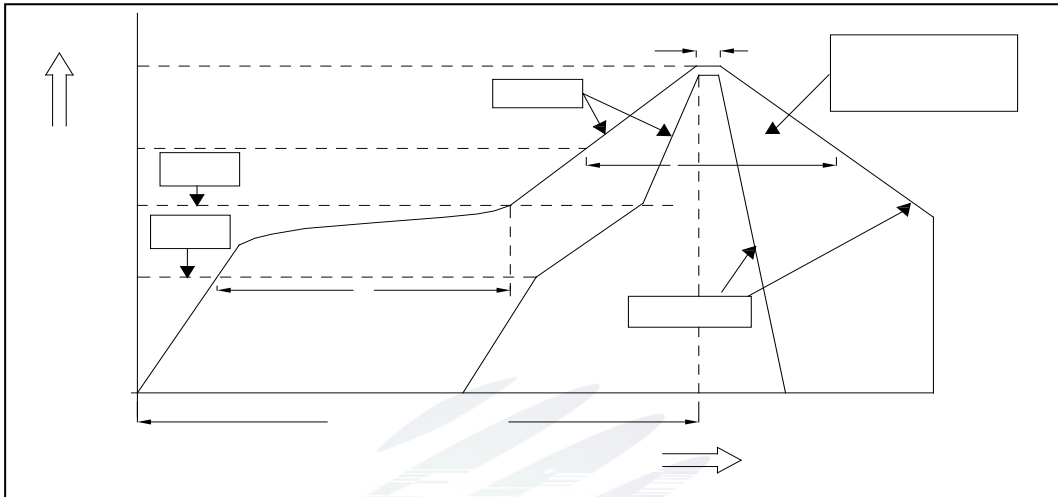
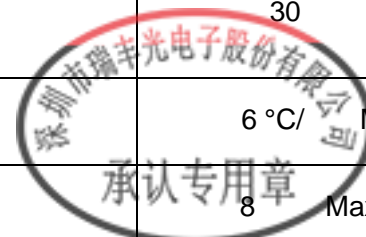


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Reflow parameters

Average temperature rise speed	T_{sm}	T_p	3 °C/ s	Max 3 °C/ s
Preheating: minimum temperature	(T _{smmin})		150 °C	
Preheating: Max temperature	(T _{smmax})		200 °C	
Preheating: Time	T _{smmin}	T _{smmax}	60 - 120	60s-120s
Time limited to maintain high temperature: the temperature	(T _l)		217 °C	
Time limited to maintain high temperature: The Time	(t _l)		60	Max 60s
Peak /Classification of temperature:	/	(T _p)	260 °C	
Time limit classification of peak temperature time	t _p		10	Max 10s
(T _p) 5 °C	Hold time within 5 °C with the		30	Max 30s
actual peak temperature (TP)				
Cooling speed			6 °C/ s	Max 6 °C/ s
25 °C	Needed time from 25 °C to T _p		8	Max 8 minutes



4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED

LED

100PPM.

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement.

LED

LED

REFOND

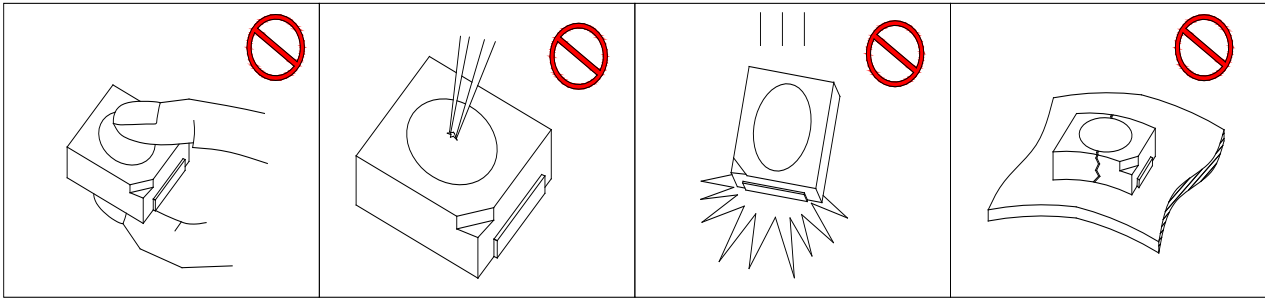


Fig 4-1 Handling Precautions

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design.

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED



Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	Recommended for use within 24 hours 24

Baking

24





Declare

This specification is written both in English and in Chinese and the latter is formal.